# 4V Drive Pch MOSFET RSR015P03

#### Structure

Silicon P-channel MOSFET

### ● Features

- 1) Low On-resistance
- 2) Space saving-small surface mount package (TSMT3)
- 3) 4V drive

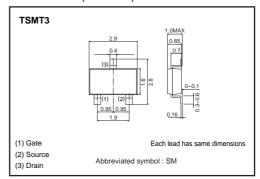
## Applications

Switching

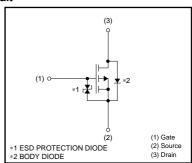
## Packaging specifications

	Package	Taping	
Туре	Code	TL	
	Basic ordering unit (pieces)	3000	
RSR015P03		0	

## ●Dimensions (Unit:mm)



#### •Inner circuit



## ● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-source voltage		$V_{DSS}$	-30	V
Gate-source voltage		V <sub>GSS</sub>	±20	V
Drain current	Continuous	ID	±1.5	Α
Drain current	Pulsed	I <sub>DP</sub> *1	±6	Α
Source current	Continuous	Is	-0.5	А
(Body diode)	Pulsed	I <sub>SP</sub> *1	-6	Α
Total power dissipation		P <sub>D</sub> *2	1	W
Channel temperature		Tch	150	°C
Range of storage temperature		Tstg	-55 to +150	°C

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 Mounted on a ceramic board

## Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth(ch-a)*	125	°C/W

<sup>\*</sup> Mounted on a ceramic board



# ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	1	-	±10	μΑ	Vgs=±20V, Vps=0V
Drain-source breakdown voltage	V <sub>(BR)</sub> DSS	-30	_	_	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	IDSS	-	_	-1	μΑ	V <sub>DS</sub> = -30V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-1.0	_	-2.5	V	$V_{DS}=-10V$ , $I_{D}=-1mA$
		-	170	235	mΩ	I <sub>D</sub> = -1.5A, V <sub>G</sub> S= -10V
Static drain-source on-state resistance	R <sub>DS (on)</sub> *	-	270	375	mΩ	I <sub>D</sub> = -0.8A, V <sub>G</sub> S= -4.5V
resistance		-	320	440	mΩ	I <sub>D</sub> = -0.8A, V <sub>G</sub> S= -4V
Forward transfer admittance	Y <sub>fs</sub> *	0.9	-	_	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -0.8A
Input capacitance	Ciss	-	190	_	pF	V <sub>DS</sub> = -10V
Output capacitance	Coss	_	45	_	pF	Vgs=0V
Reverse transfer capacitance	Crss	_	30	_	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub> *	-	6	_	ns	Vpp≒ –15V
Rise time	tr *	-	8	_	ns	ID= -0.8A
Turn-off delay time	t <sub>d (off)</sub> *	_	22	_	ns	V <sub>GS</sub> = -10V R <sub>L</sub> =19Ω
Fall time	t <sub>f</sub> *	-	6	_	ns	R <sub>G</sub> =10Ω
Total gate charge	Qg *	_	2.6	_	nC	V <sub>DD</sub> ≒-15V V <sub>GS</sub> =-5V
Gate-source charge	Q <sub>gs</sub> *	-	1.0	-	nC	I <sub>D</sub> = -1.5A
Gate-drain charge	Q <sub>gd</sub> *	_	0.7	_	nC	R <sub>L</sub> =10Ω R <sub>G</sub> =10Ω

\*Pulsed

# ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	Vsp	-	_	-1.2	V	I <sub>S</sub> = -0.5A, V <sub>GS</sub> =0V

#### Electrical characteristics curves

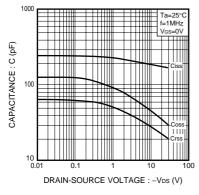


Fig.1 Typical Capacitance vs. Drain-Source Voltage

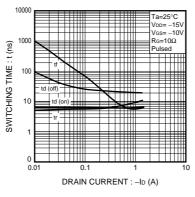


Fig.2 Switching Characteristics

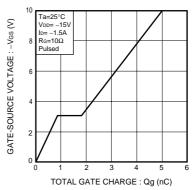


Fig.3 Dynamic Input Characteristics

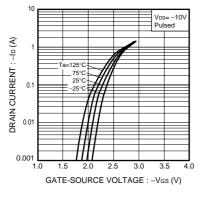


Fig.4 Typical Transfer Characteristics

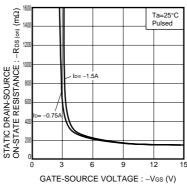


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

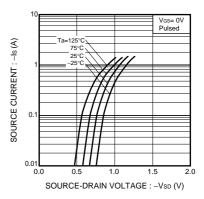


Fig.6 Source Current vs. Source-Drain Voltage

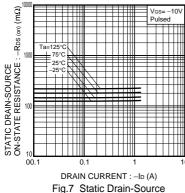
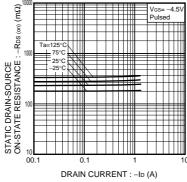
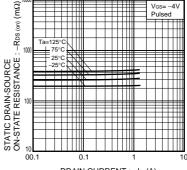


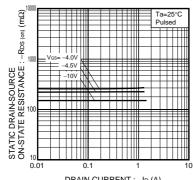
Fig.7 Static Drain-Source
On-State Resistance vs.
Drain current (I)



DRAIN CURRENT : -ID (A)
Fig.8 Static Drain-Source
On-State Resistance vs.
Drain current ( II )



DRAIN CURRENT : -ID (A)
Fig.9 Static Drain-Source
On-State Resistance vs.
Drain current ( III )



DRAIN CURRENT: -Io (A)
Fig.10 Static Drain-Source
On-State Resistance vs.
Drain current ( IV )

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